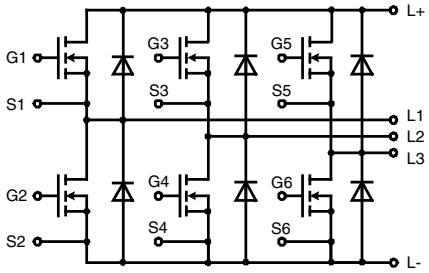
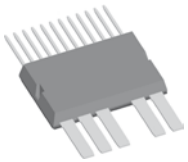
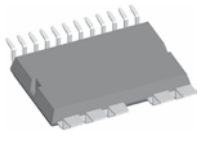
Three phase full Bridge

with Trench MOSFETs
in DCB isolated high current package

V_{DSS} = 85 V
I_{D25} = 103 A
$R_{DSon\ typ.}$ = 5.5 mΩ




Straight leads


Surface Mount Device

MOSFETs

Symbol	Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 150°C	85	V
V_{GS}		± 20	V
I_{D25}	T_C = 25°C	103	A
I_{D90}	T_C = 90°C	77	A
I_{D110}	T_C = 110°C	68	A
I_{F25}	T_C = 25°C (diode)	tbd	A
I_{F90}	T_C = 90°C (diode)	tbd	A
I_{F110}	T_C = 110°C (diode)	tbd	A

Symbol	Conditions		Characteristic Values (T_J = 25°C, unless otherwise specified) min.	typ.	max.	
R_{DSon} [1]	on chip level at V_{GS} = 10 V; I_D = 75 A	T_J = 25°C		5.5	6.2	mΩ
		T_J = 125°C		12.7		mΩ
$V_{GS(th)}$	V_{DS} = 20 V; I_D = 250 µA		2.0		4.0	V
I_{DSS}	V_{DS} = V_{DSS}; V_{GS} = 0 V	T_J = 25°C			5	µA
		T_J = 125°C		100		µA
I_{GSS}	V_{GS} = ± 20 V; V_{DS} = 0 V				0.2	µA
Q_g	V_{GS} = 10 V; V_{DS} = 42 V; I_D = 75 A			114		nC
Q_{gs}				30		nC
Q_{gd}				35		nC
$t_{d(on)}$	inductive load V_{GS} = 10 V; V_{DS} = 42 V; I_D = 75 A; R_G = 39 Ω; T_J = 125°C			tbd		ns
t_r				tbd		ns
$t_{d(off)}$				tbd		ns
t_f				tbd		ns
E_{on}				tbd		mJ
E_{off}				tbd		mJ
E_{recoff}				tbd		mJ
R_{thJC}	with heat transfer paste (IXYS test setup)				1.0	K/W
R_{thJH}				1.3	1.6	K/W

[1] $V_{DS} = I_D \cdot (R_{DS(on)} + R_{Pin\ to\ Chip})$

Applications

AC drives
- in automobiles
  - electric power steering
  - starter generator
- in industrial vehicles
  - propulsion drives
  - fork lift drives
- in battery supplied equipment

Features

- MOSFETs in trench technology:
  - low RDSon
  - optimized intrinsic reverse diode
- package:
  - high level of integration
  - high current capability 300 A max.
  - aux. terminals for MOSFET control
  - terminals for soldering or welding connections
  - isolated DCB ceramic base plate with optimized heat transfer
- Space and weight savings

Package options

- 2 lead forms available
  - straight leads (SL)
  - SMD lead version (SMD)

Source-Drain Diode

Symbol	Conditions	Characteristic Values (T_J = 25°C, unless otherwise specified) min.	typ.	max.	
V_{SD}	(diode) I_F = 100 A; V_{GS} = 0 V		0.9	1.2	V
t_{rr}	I_F = 100 A; -di$_F$/dt = 800 A/µs; V_R = 24 V T_{VJ} = 125°C		tbd		ns
Q_{RM}			tbd		µC
I_{RM}			tbd		A

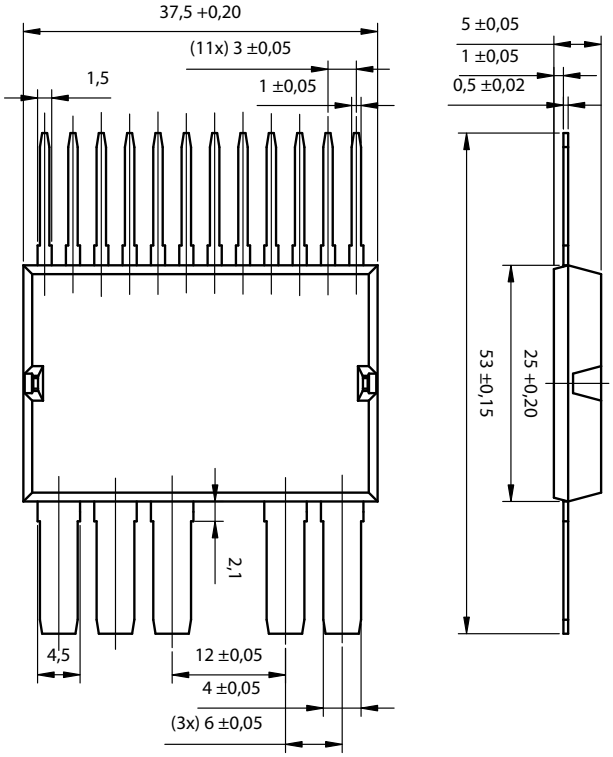
Component

Symbol	Conditions	Maximum Ratings	
I_{RMS}	per pin in main current paths (P+, N-, L1, L2, L3) may be additionally limited by external connections	300	A
T_J		-55...+175	°C
T_{stg}		-55...+125	°C
V_{ISOL}	$I_{ISOL} \leq$ 1 mA, 50/60 Hz, f = 1 minute	1000	V~
F_C	mounting force with clip	50 - 250	N

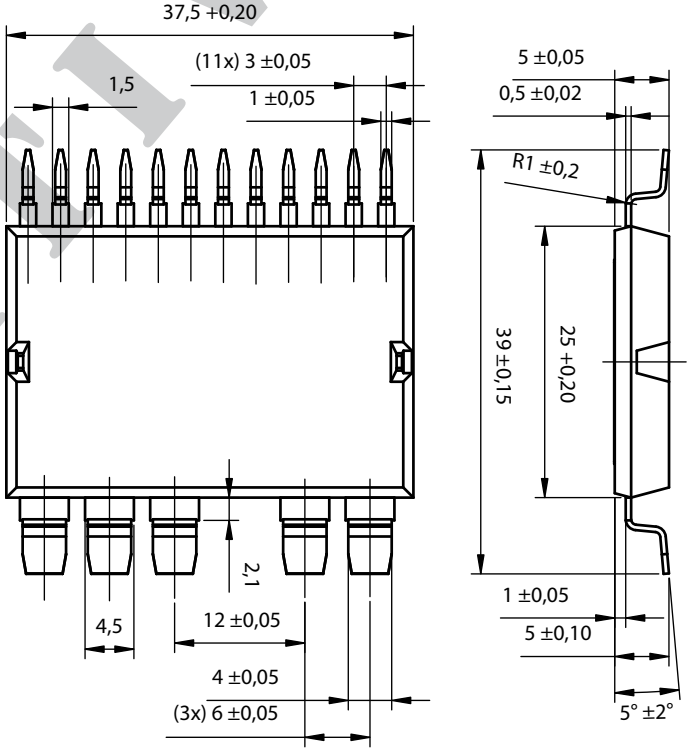
Symbol	Conditions	Characteristic Values min.	typ.	max.	
$R_{pin\ to\ chip}$ [1)]	L+ to L1/L2/L3 or L- to L1/L2/L3		1.0		mΩ
C_P	coupling capacity between shorted pins and mounting tab in the case		160		pF
Weight			25		g

[1)] $V_{DS} = I_D \cdot (R_{DS(on)} + R_{Pin\ to\ Chip})$

Straight Leads GWM 100-085X1-SL



Surface Mount Device GWM 100-085X1-SMD



Leads	Ordering	Part Name & Packing Unit Marking	Part Marking	Delivering Mode	Base Qty.	Ordering Code
Straight	Standard	GWM 100-0085X1 - SL	GWM 100-0085X1	Blister	28	tbd
SMD	Standard	GWM 100-0085X1 - SMD	GWM 100-0085X1	Blister	28	tbd

IXYS reserves the right to change limits, test conditions and dimensions.

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